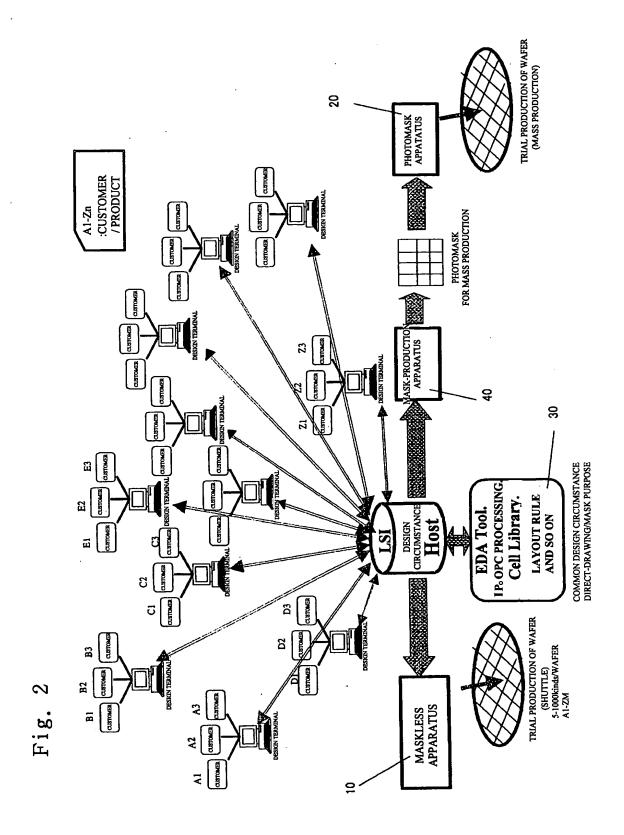


Fig.



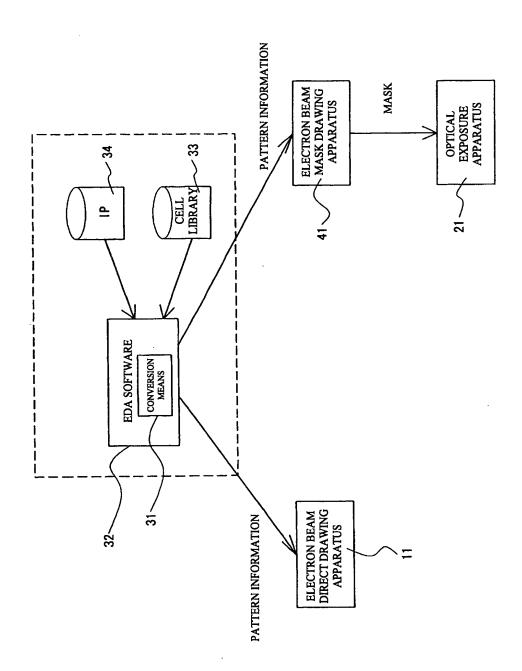
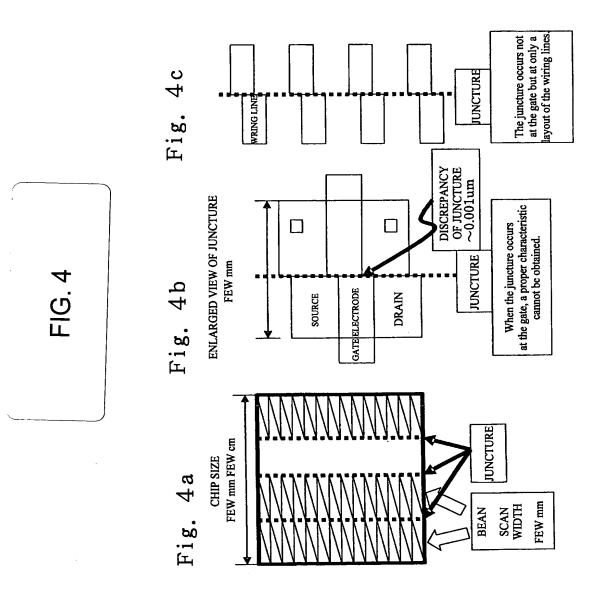
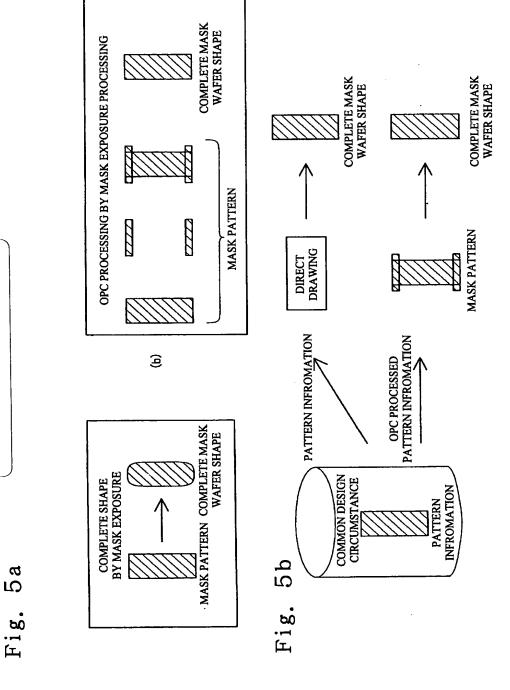


Fig. 3

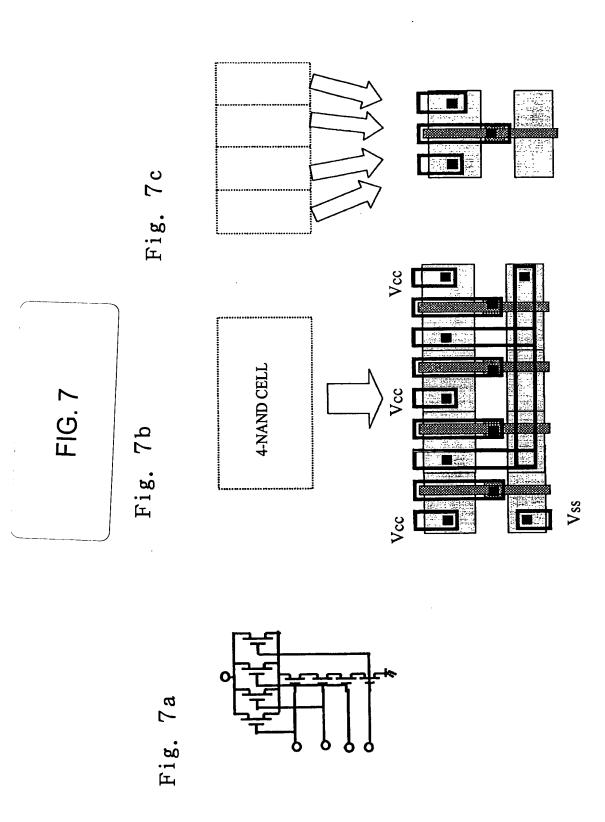




**--**-

Fig. 6

	PHOTOMASK-PURPOSE (PRIOR ART) CELL LIBRARY		COMMON (MASK/DIRECT-DRAWING) CELL LIBRARY	
	CELL PATTERN SHAPE	NUMBER OF SHOTS	CELL PATTERN SHAPE	NUMBER OF SHOTS
WHOLE VIEW				
SOURCE/ DRAIN PATTERN (PATTERN COMPONENT		3 KINDS		3 KINDS
GATE PATTERN PATTERN COMPONENT		3 KINDS		1 KINDS
WIRING LINE (AL/C <sub>u</sub> ) THROUGH HOLE PATTERN ATTERN COMPONENT) (PATTERN COMPONENT)		3 KINDS		1 KINDS
WIRING LINE (AL/Cu) T PATTERN COMPONENT)		3 KINDS		1 KINDS
NUMBER OF TOTAL SHOTS	3+3+3+3=12		3+1+1+1=6	
EXPLANATION OF PATTERN	CELL AREA WIRING LINE THROUGH HOLE SOURCE DRAIN GATE			



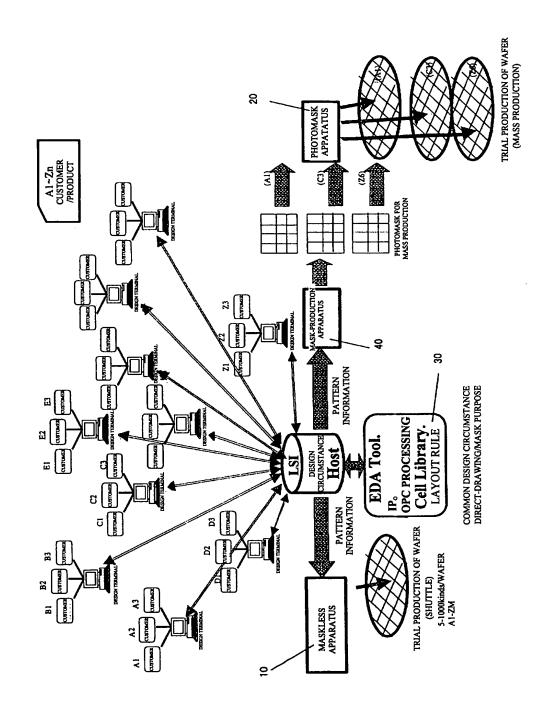
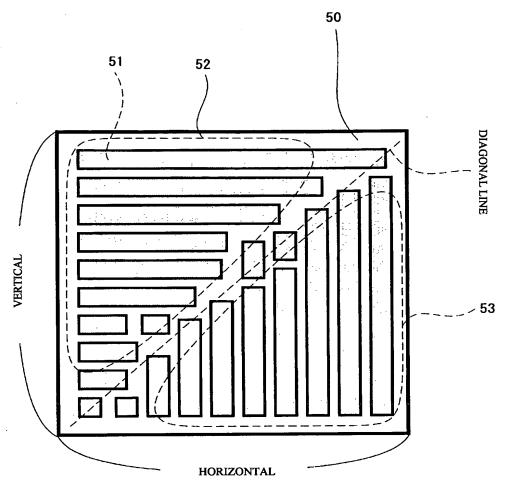


Fig.

 $\infty$ 

Fig. 9



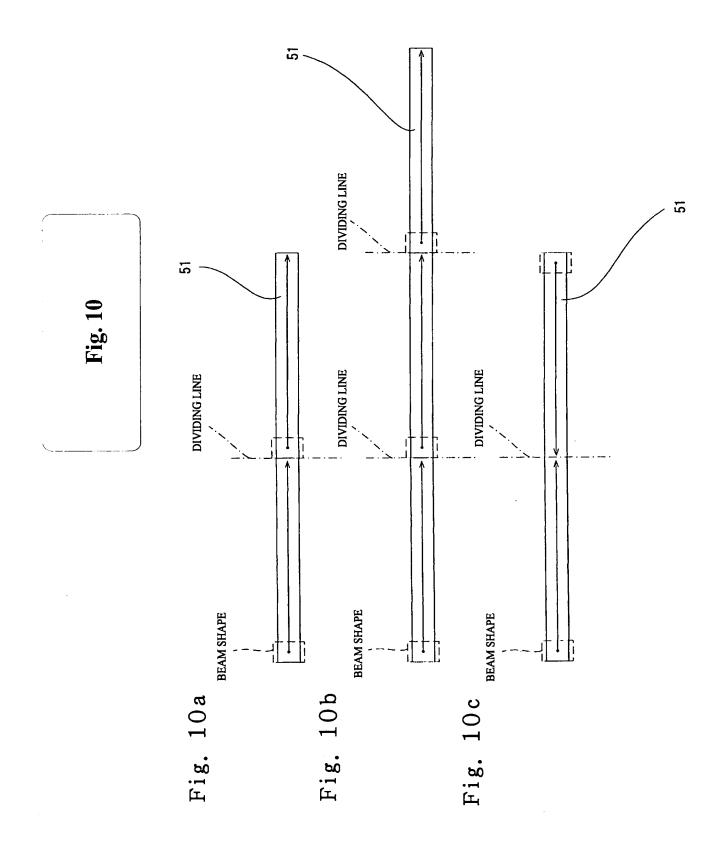
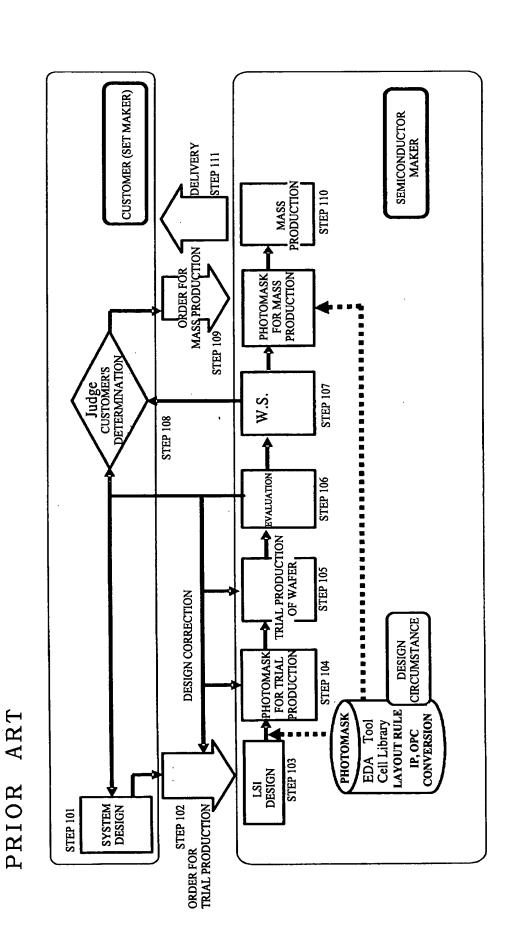


Fig. 11



RODUCTION **STEP 211** 

EVALUATION

STEP 210

MASS

DELIVERY

**STEP 212** 

SEMICONDUCTOR MAKER B CUSTOMER (SET MAKER) DESIGN CIRCUMSTANCE PRODUCTION STEP 209 EDA Tool DE CEIL CEIL LIBRARY OPPE CONVERSION AND SO ON PHOTOMASK ORDER FOR STEP 208 MASS PRODUCTION PHOTOMASK FOR MASS PRODUCTION Judge CUSTOMER'S DETERMINATION **STEP 207 STEP 206** SEMICONDUCTOR MAKER A ₩.S. VALUATION **STEP 205** TRIAL PRODUCTION OF WAFER DESIGN CORRECTION DIRECT DRAWING ON WAFER DESIGN CIRCUMSTANCE STEP 204 DIRECT-DRAWING LAYOUT RULE Cell Library EDA Tool PRIOR ART LSI DESIGN 싪 ORDER FOR TRIAL PRODUCTION STEP 202 **STEP 201** SYSTEM DESIGN STEP 203 Fig. 12

PRIOR ART

102

103

MN NOPP

109

Fig. 13

